

# PMEG3020BEP

2 A low  $V_F$  MEGA Schottky barrier rectifier

Rev. 01 — 16 October 2009

Product data sheet

## 1. Product profile

### 1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD128 small and flat lead Surface-Mounted Device (SMD) plastic package.

### 1.2 Features

- Average forward current:  $I_{F(AV)} \leq 2$  A
- Reverse voltage:  $V_R \leq 30$  V
- Low forward voltage
- High power capability due to clip-bond technology
- AEC-Q101 qualified
- Small and flat lead SMD plastic package

### 1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Low power consumption applications

### 1.4 Quick reference data

**Table 1. Quick reference data**



$T_j = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	square wave; $\delta = 0.5$ ; $f = 20$ kHz				
		$T_{amb} \leq 100^\circ\text{C}$	[1] -	-	2	A
		$T_{sp} \leq 140^\circ\text{C}$	-	-	2	A
$V_R$	reverse voltage		-	-	30	V
$V_F$	forward voltage	$I_F = 2$ A	-	400	450	mV
$I_R$	reverse current	$V_R = 30$ V	-	35	100	$\mu\text{A}$

[1] Device mounted on a ceramic Printed-Circuit Board (PCB),  $\text{Al}_2\text{O}_3$ , standard footprint.

## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	cathode		 sym001
2	anode		

[1] The marking bar indicates the cathode.

## 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG3020BEP	-	plastic surface-mounted package; 2 leads	SOD128

## 4. Marking

Table 4. Marking codes

Type number	Marking code
PMEG3020BEP	A4

## 5. Limiting values

Table 5. Limiting values

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
$V_R$	reverse voltage	$T_j = 25\text{ }^{\circ}\text{C}$	-	30	V
$I_{F(AV)}$	average forward current	square wave; $\delta = 0.5$ ; $f = 20\text{ kHz}$			
		$T_{amb} \leq 100\text{ }^{\circ}\text{C}$	[1] -	2	A
		$T_{sp} \leq 140\text{ }^{\circ}\text{C}$	-	2	A
$I_{FSM}$	non-repetitive peak forward current	square wave; $t_p = 8\text{ ms}$	[2] -	50	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ }^{\circ}\text{C}$	[3][4] -	625	mW
			[3][5] -	1050	mW
			[3][1] -	2100	mW

**Table 5. Limiting values ...continued***In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-55	+150	°C
$T_{stg}$	storage temperature		-65	+150	°C

[1] Device mounted on a ceramic PCB,  $Al_2O_3$ , standard footprint.[2]  $T_j = 25$  °C prior to surge.

[3] Reflow soldering is the only recommended soldering method.

[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[5] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

## 6. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]			
			[3] -	-	200	K/W
			[4] -	-	120	K/W
			[5] -	-	60	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[6] -	-	12	K/W

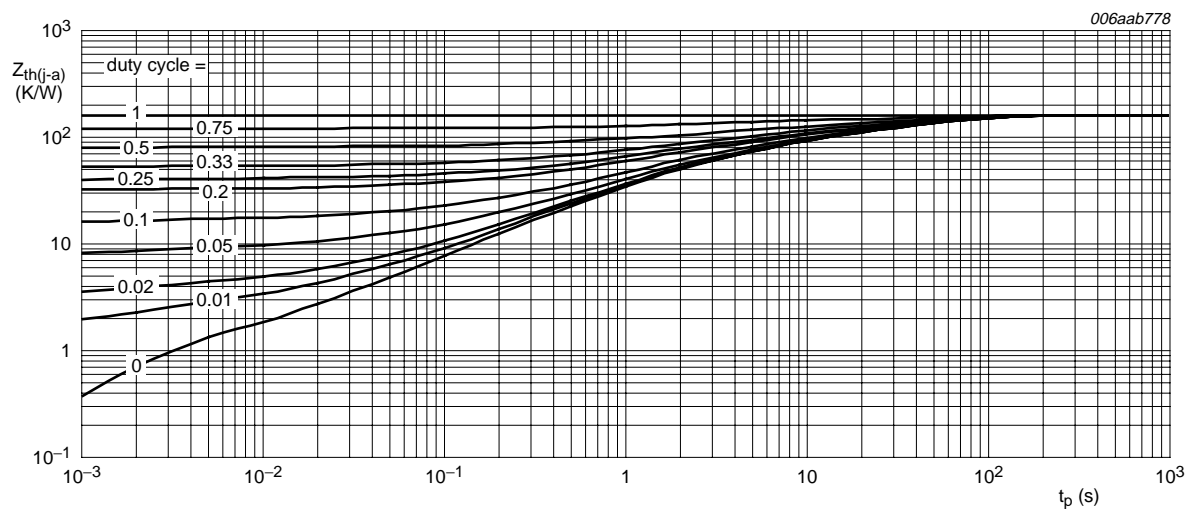
[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.

[2] Reflow soldering is the only recommended soldering method.

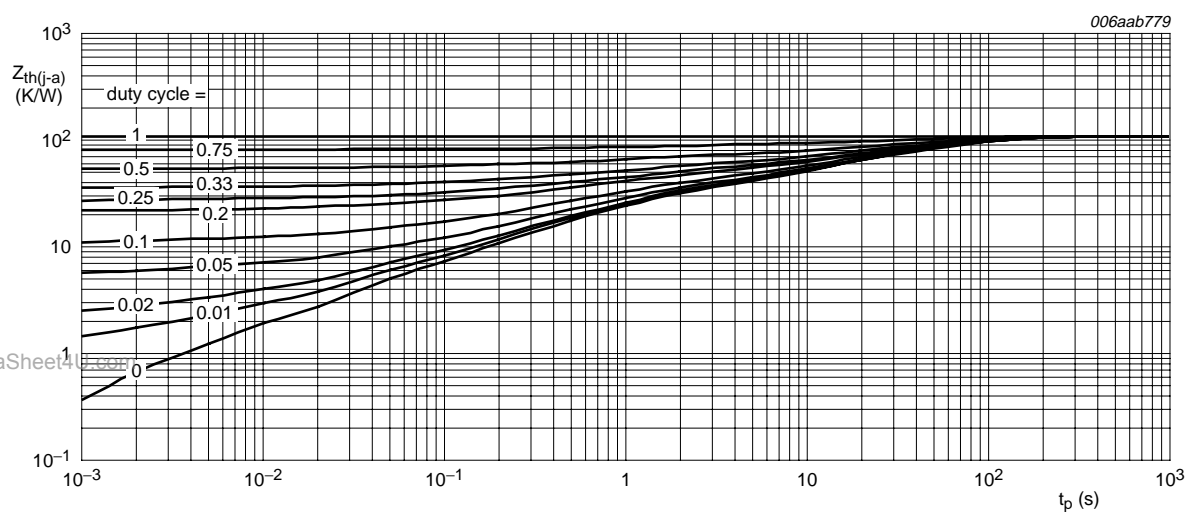
[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.[5] Device mounted on a ceramic PCB,  $Al_2O_3$ , standard footprint.

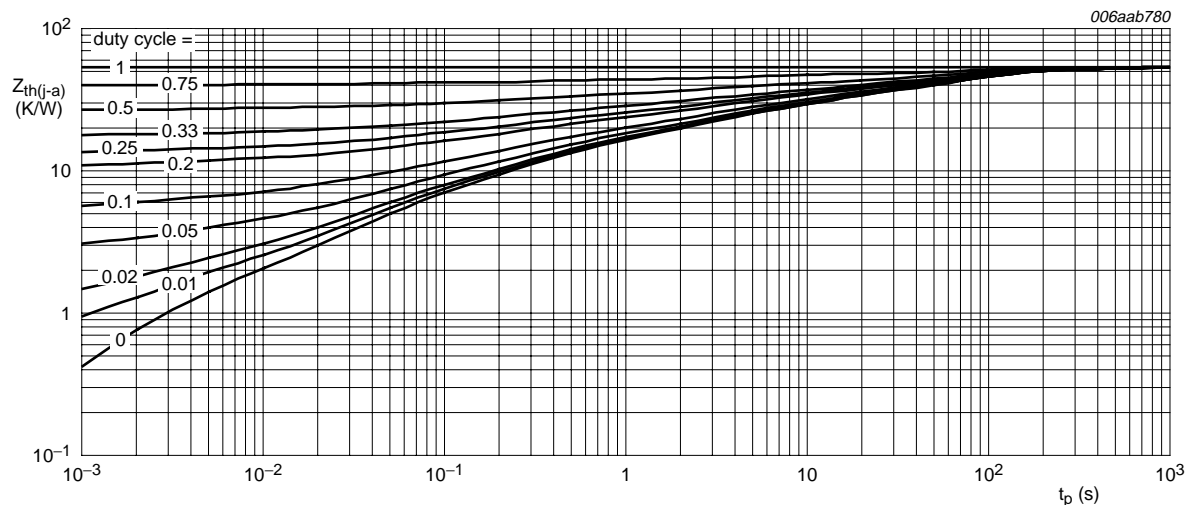
[6] Soldering point of cathode tab.



**Fig 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**



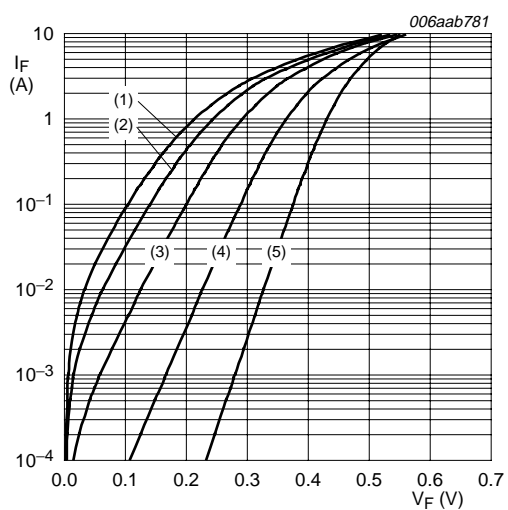
**Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**

Ceramic PCB,  $\text{Al}_2\text{O}_3$ , standard footprint**Fig 3.** Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 7. Characteristics

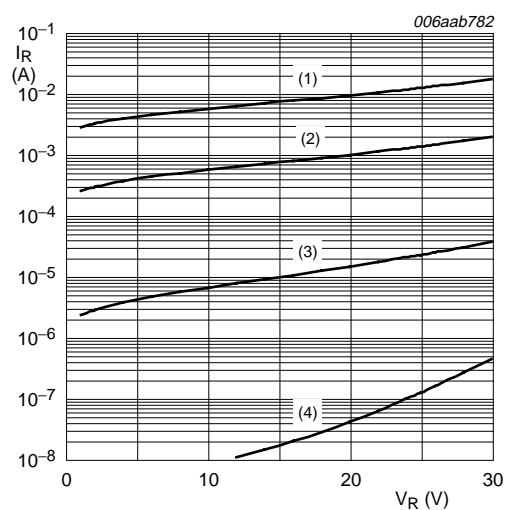
**Table 7.** Characteristics $T_j = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_F$	forward voltage	$I_F = 0.1\text{ A}$	-	290	340	mV
		$I_F = 0.5\text{ A}$	-	340	400	mV
		$I_F = 1\text{ A}$	-	365	420	mV
		$I_F = 1.5\text{ A}$	-	385	440	mV
		$I_F = 2\text{ A}$	-	400	450	mV
$I_R$	reverse current	$V_R = 5\text{ V}$	-	4	-	$\mu\text{A}$
		$V_R = 10\text{ V}$	-	6	-	$\mu\text{A}$
		$V_R = 30\text{ V}$	-	35	100	$\mu\text{A}$
$C_d$	diode capacitance	$f = 1\text{ MHz}$				
		$V_R = 1\text{ V}$	-	340	-	pF
		$V_R = 10\text{ V}$	-	120	-	pF



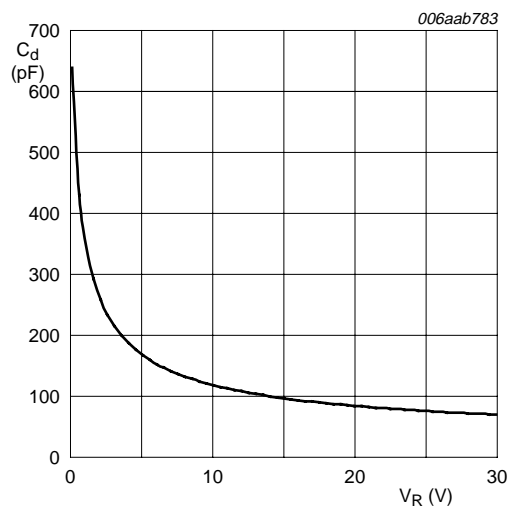
- (1)  $T_j = 150\text{ °C}$
- (2)  $T_j = 125\text{ °C}$
- (3)  $T_j = 85\text{ °C}$
- (4)  $T_j = 25\text{ °C}$
- (5)  $T_j = -40\text{ °C}$

**Fig 4. Forward current as a function of forward voltage; typical values**



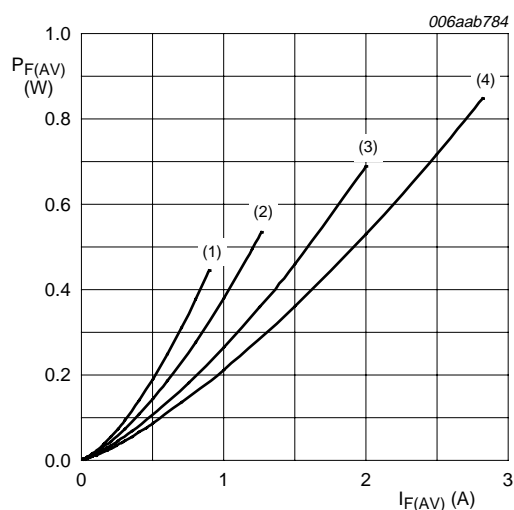
- (1)  $T_j = 125\text{ °C}$
- (2)  $T_j = 85\text{ °C}$
- (3)  $T_j = 25\text{ °C}$
- (4)  $T_j = -40\text{ °C}$

**Fig 5. Reverse current as a function of reverse voltage; typical values**



$f = 1\text{ MHz}$ ;  $T_{\text{amb}} = 25\text{ °C}$

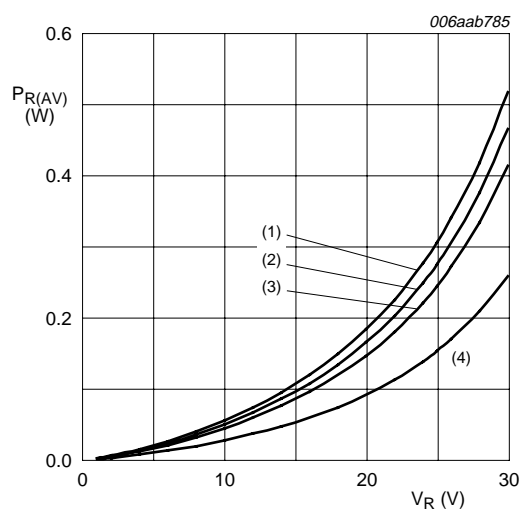
**Fig 6. Diode capacitance as a function of reverse voltage; typical values**



$T_j = 150\text{ }^{\circ}\text{C}$

- (1)  $\delta = 0.1$
- (2)  $\delta = 0.2$
- (3)  $\delta = 0.5$
- (4)  $\delta = 1$

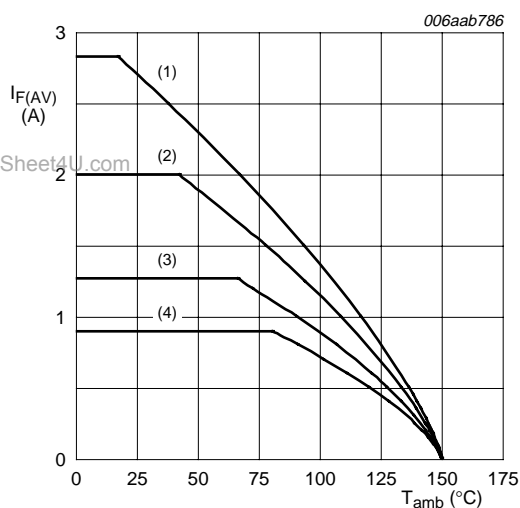
**Fig 7. Average forward power dissipation as a function of average forward current; typical values**



$T_j = 125\text{ }^{\circ}\text{C}$

- (1)  $\delta = 1$
- (2)  $\delta = 0.9$
- (3)  $\delta = 0.8$
- (4)  $\delta = 0.5$

**Fig 8. Average reverse power dissipation as a function of reverse voltage; typical values**

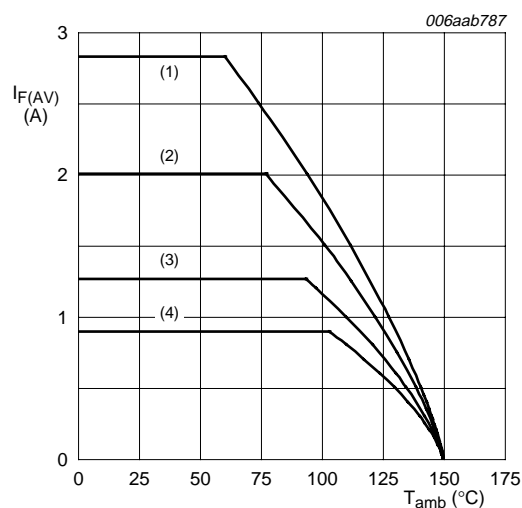


FR4 PCB, standard footprint

$T_j = 150\text{ }^{\circ}\text{C}$

- (1)  $\delta = 1$ ; DC
- (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$
- (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$
- (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig 9. Average forward current as a function of ambient temperature; typical values**

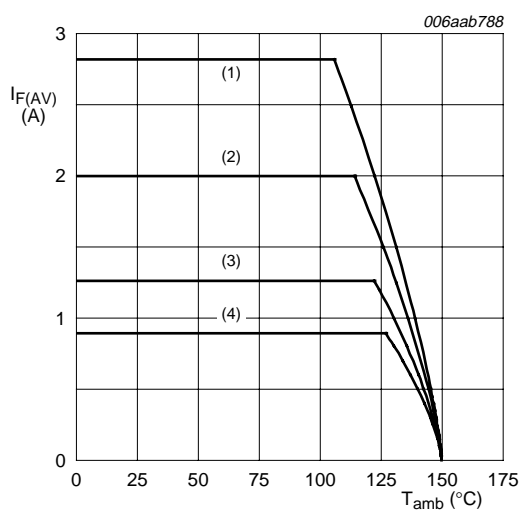


FR4 PCB, mounting pad for cathode  $1\text{ cm}^2$

$T_j = 150\text{ }^{\circ}\text{C}$

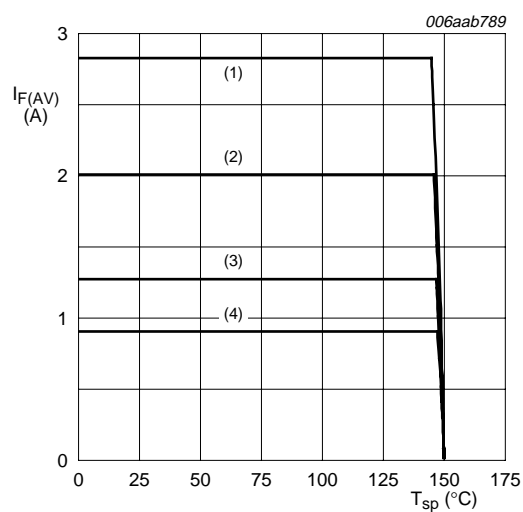
- (1)  $\delta = 1$ ; DC
- (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$
- (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$
- (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig 10. Average forward current as a function of ambient temperature; typical values**

Ceramic PCB,  $Al_2O_3$ , standard footprint $T_j = 150\text{ °C}$ 

- (1)  $\delta = 1$ ; DC
- (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$
- (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$
- (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig 11. Average forward current as a function of ambient temperature; typical values**

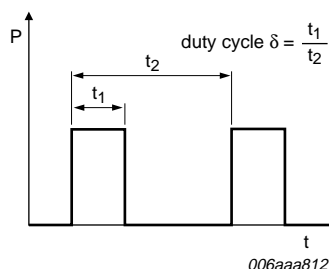
 $T_j = 150\text{ °C}$ 

- (1)  $\delta = 1$ ; DC
- (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$
- (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$
- (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig 12. Average forward current as a function of solder point temperature; typical values**



## 8. Test information



**Fig 13. Duty cycle definition**

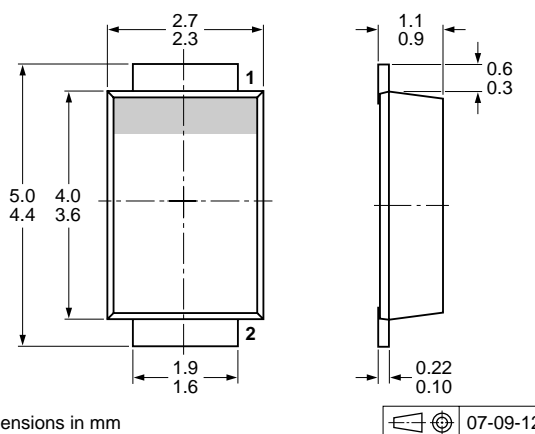
The current ratings for the typical waveforms as shown in [Figure 9](#), [10](#), [11](#) and [12](#) are calculated according to the equations:  $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current,

$I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_M \times \sqrt{\delta}$  with  $I_{RMS}$  defined as RMS current.

### 8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

## 9. Package outline



**Fig 14. Package outline SOD128**

## 10. Packing information

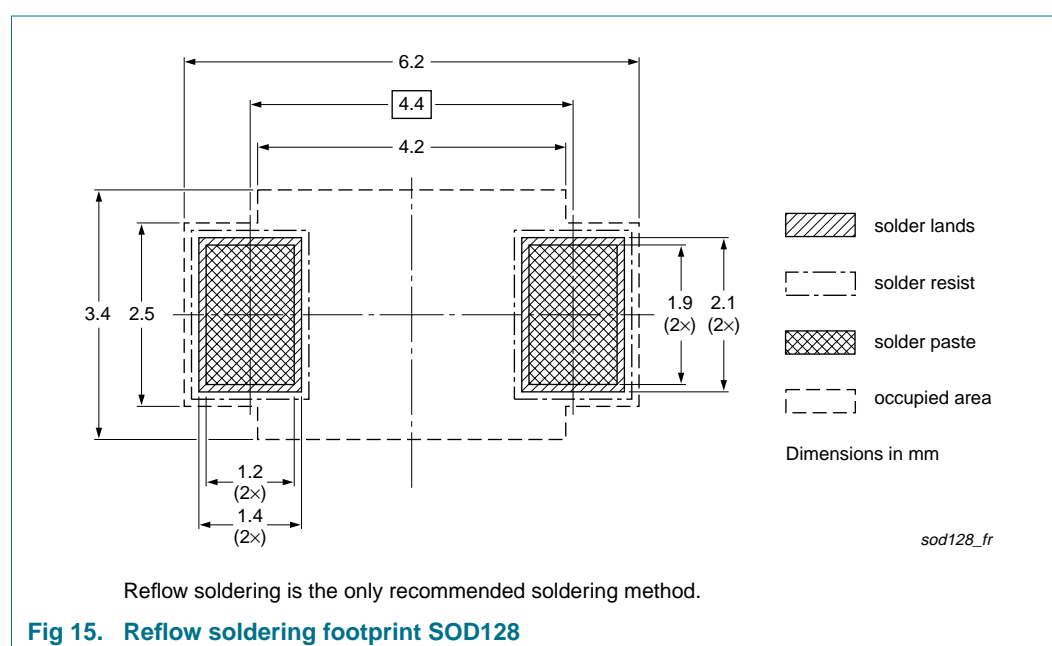
**Table 8. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

Type number	Package	Description	Packing quantity
			<b>3000</b>
PMEG3020BEP	SOD128	4 mm pitch, 12 mm tape and reel	-115

[1] For further information and the availability of packing methods, see [Section 14](#).

## 11. Soldering



## 12. Revision history

**Table 9.** Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMEG3020BEP_1	20091016	Product data sheet	-	-

## 13. Legal information

### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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